

TAIWAN SEMICONDUCTOR MANUFACTURING CO LTD  
Form 6-K  
February 08, 2016

1934 Act Registration No. 1-14700

**SECURITIES AND EXCHANGE COMMISSION**

**Washington, DC 20549**

**FORM 6-K**

**REPORT OF FOREIGN PRIVATE ISSUER**

**PURSUANT TO RULE 13a-16 OR 15d-16**

**OF THE SECURITIES EXCHANGE ACT OF 1934**

**For the month of February 2016**

**Taiwan Semiconductor Manufacturing Company Ltd.**

**(Translation of Registrant's Name Into English)**

**No. 8, Li-Hsin Rd. 6,**

**Hsinchu Science Park,**

**Taiwan**

**(Address of Principal Executive Offices)**

(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F       Form 40-F

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes       No

(If  Yes is marked, indicated below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82: .)

**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Taiwan Semiconductor Manufacturing Company Ltd.

Date: **February** 6, 2016

By /s/ Lora Ho  
Lora Ho  
Senior Vice President & Chief Financial Officer

**TSMC Assessing February 6 Earthquakes And Planning Recovery**

Hsinchu, Taiwan, R.O.C. - February 6, 2016 - TSMC today announced that the earthquake of 6.4 magnitude which struck southern Taiwan at 3:57 am on February 6, 2016 did not cause any serious personnel injuries nor any structural or facility damage to the Company's Fab 14 and Fab 6 manufacturing sites in the Tainan Science Park. The earthquake also did not cause equipment to shift position.

Damage to wafers in progress remains under assessment, but TSMC's initial estimate is that more than 95 percent of the tools can be fully restored to normal in two to three days. The company is deploying personnel from Hsinchu and Taichung sites to support recovery in Tainan, and does not expect the earthquake to affect first quarter 2016 wafer shipment by more than 1 percent. TSMC will soon notify affected customers and will recover any lost production as soon as possible.

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**TSMC Spokesperson:**

Ms. Lora Ho

Senior Vice President and CFO

Tel: 886-3-566-4602

**TSMC Acting Spokesperson:**

Dr. Elizabeth Sun

Director

Corporate Communication

Division

Tel: 886-3-568-2085

Mobile: 886-988-937999

E-Mail: elizabeth\_sun@tsmc.com